MAX202 5-V Dual RS-232 Line Driver and Receiver With ±15-kV ESD Protection

1 Features

- Meets or exceeds the requirements of TIA/EIA-232-F and ITU v.28 standards
- ESD protection for RS-232 bus pins: ±15kV human-body model
- Operates at 5V V_{CC} supply
- Operates up to 120kbit/s
- Two drivers and two receivers
- Latch-up performance exceeds 100mA Per JESD 78, class II

2 Applications

- Battery-powered systems
- Notebooks
- Laptops
- Palmtop PCs
- Hand-held equipment

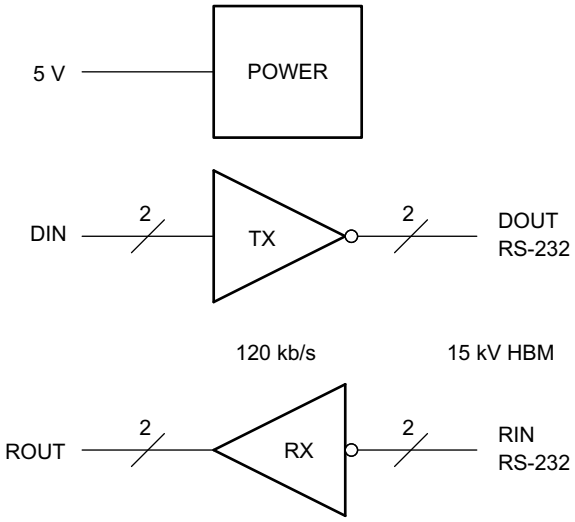
3 Description

The MAX202 device consists of two line drivers, two line receivers, and a dual charge-pump circuit with ±15kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 5V supply. The device operates at data signaling rates up to 120kbit/s and a maximum of 30V/µs driver output slew rate.

Package Information

PART NUMBER	PACKAGE(1)	PACKAGE SIZE(2)
MAX202	SOIC (D) (16)	9.9mm × 6mm
	SOIC WIDE (DW) (16)	10.4mm × 10.3mm
	TSSOP (PW) (16)	5 mm x 6.4mm

(1) For more Information, see Section 10.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.



Block Diagram

Table of Contents

4 Pin Configuration and Functions

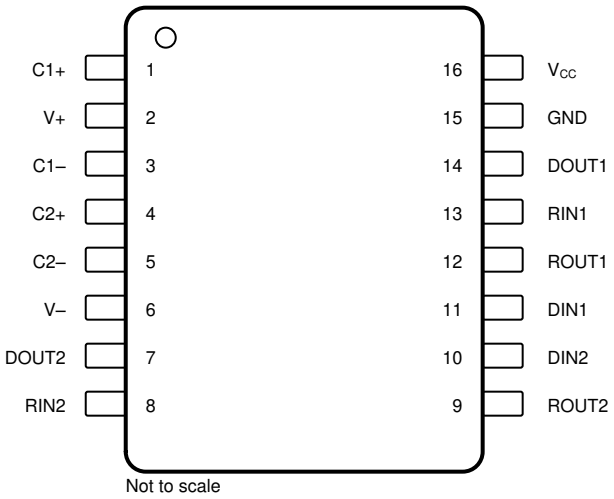


Figure 4-1. D, DW, or PW Package, 16-Pin SOIC or TSSOP (Top View)

Table 4-1. Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	C1+	—	Positive lead of C1 capacitor
2	V+	O	Positive charge pump output for storage capacitor only
3	C1–	—	Negative lead of C1 capacitor
4	C2+	—	Positive lead of C2 capacitor
5	C2–	—	Negative lead of C2 capacitor
6	V–	O	Negative charge pump output for storage capacitor only
7	DOUT2	O	RS-232 line data output (to remote RS-232 system)
8	RIN2	I	RS-232 line data input (from remote RS-232 system)
9	ROUT2	O	Logic data output (to UART)
10	DIN2	I	Logic data input (from UART)
11	DIN1	I	Logic data input (from UART)
12	ROUT1	O	Logic data output (to UART)
13	RIN1	I	RS-232 line data input (from remote RS-232 system)
14	DOUT1	O	RS-232 line data output (to remote RS-232 system)
15	GND	—	Ground
16	V_{CC}	—	Supply voltage, connect to external 5V power supply

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
Supply voltage, V_{CC} (2)		–0.3	6	V
Positive charge pump voltage, V+(2)		V_{CC} – 0.3	14	V
Negative charge pump voltage, V–(2)		–14	0.3	V
Input voltage, V_I	Drivers	–0.3	V+ + 0.3	V
	Receivers		±30	
Output voltage, V_O	Drivers	V– – 0.3	V+ + 0.3	V
	Receivers	–0.3	V_{CC} + 0.3	
Short-circuit duration, D_{OUT}		Continuous		
Operating junction temperature, T_J			150	°C
Storage temperature, T_{stg}		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages are with respect to network GND.

5.2 ESD Ratings

				VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	Pins 7, 8, 13, and 14	±15000	V
			All other pins	±2000	
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)		±1500	

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted(1); see Figure 7-1)

			MIN	NOM	MAX	UNIT
	Supply voltage		4.5	5	5.5	V
V_{IH}	Driver high-level input voltage (D_{IN})		2			V
V_{IL}	Driver low-level input voltage (D_{IN})				0.8	V
V_I	Driver input voltage (D_{IN})		0		5.5	V
	Receiver input voltage		–30		30	
T_A	Operating free-air temperature	MAX202C	0		70	°C
		MAX202I	–40		85	

(1) Test conditions are C1–C4 = 0.1µF at V_{CC} = 5V ±0.5V.

5.4 Thermal Information

THERMAL METRIC(1)		D (SOIC) 16 PINS	DW (SOIC) 16 PINS	PW (TSSOP) 16 PINS	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	84.6	71.7	107.5	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	43.5	37.6	38.4	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	43.2	36.8	53.7	°C/W
ψ_{JT}	Junction-to-top characterization parameter	10.4	13.	3.2	°C/W
ψ_{JB}	Junction-to-board characterization parameter	42.8	36.4	53.1	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

5.5 Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted; see Figure 7-1)(1)

PARAMETER		TEST CONDITIONS	MIN	TYP(2)	MAX	UNIT
I_{CC}	Supply current	No load, V_{CC} = 5V		8	15	mA
DRIVER SECTION						
V_{OH}	High-level output voltage	D_{OUT} at R_L = 3kΩ to GND, D_{IN} = GND	5	9		V
V_{OL}	Low-level output voltage	D_{OUT} at R_L = 3kΩ to GND, D_{IN} = V_{CC}	–5	–9		V
I_{IH}	High-level input current	V_I = V_{CC}		0	200	µA
I_{IL}	Low-level input current	V_I at 0V		0	–200	µA
I_{OS} (3)	Short-circuit output current	V_{CC} = 5.5V, V_O = 0V		±10	±60	mA
r_O	Output resistance	V_{CC}, V+, and V– = 0V, V_O = ±2V	300			Ω
RECEIVER SECTION						
V_{OH}	High-level output voltage	I_{OH} = –1mA	3.5	V_{CC} – 0.4		V
V_{OL}	Low-level output voltage	I_{OL} = 1.6mA			0.4	V
V_{IT+}	Positive-going input threshold voltage	V_{CC} = 5V, T_A = 25°C		1.7	2.4	V
$V_{IT–}$	Negative-going input threshold voltage	V_{CC} = 5V, T_A = 25°C	0.8	1.2		V
V_{hys}	Input hysteresis (V_{IT+} – $V_{IT–}$)		0.2	0.5	1	V
r_i	Input resistance	V_I = ±3V to ±25V	3	5	7	kΩ

(1) Test conditions are C1–C4 = 0.1 µF at V_{CC} = 5V ± 0.5V.
(2) All typical values are at V_{CC} = 5V, and T_A = 25°C.
(3) Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

5.6 Switching Characteristics

over recommended ranges of suply voltage and operating free-air temperature (unless otherwise noted; see Figure 7-1)(1)

PARAMETER		TEST CONDITIONS	MIN	TYP(2)	MAX	UNIT
DRIVER SECTION						
	Maximum data rate	C_L = 50pF to 1000pF, R_L = 3kΩ to 7kΩ one D_{OUT} switching, see Figure 6-1	120			kbit/s
$t_{PLH(D)}$	Propagation delay time, low- to high-level output	C_L = 2500pF, R_L = 3kΩ, all drivers loaded, see Figure 6-1		2		µs
$t_{PHL(D)}$	Propagation delay time, high- to low-level output	C_L = 2500pF, R_L = 3kΩ, all drivers loaded, see Figure 6-1		2		µs
$t_{sk(p)}$	Pulse skew(3)	C_L = 150 to 2500pF, R_L = 3kΩ to 7 kΩ, see Figure 6-2		300		ns
SR(tr)	Slew rate, transition region	C_L = 50 to 1000pF, R_L = 3kΩ to 7 kΩ, V_{CC} = 5V, see Figure 6-1	3	6	30	V/µs
RECEIVER SECTION (SEE Figure 6-3)						
$t_{PLH(R)}$	Propagation delay time, low- to high-level output	C_L = 150pF		0.5	10	µs
$t_{PHL(R)}$	Propagation delay time, high- to low-level output	C_L = 150pF		0.5	10	µs
$t_{sk(p)}$	Pulse skew(3)	C_L = 150pF		300		ns

(1) Test conditions are C1–C4 = 0.1µF at V_{CC} = 5V ± 0.5V.
(2) All typical values are at V_{CC} = 5V, and T_A = 25°C.
(3) Pulse skew is defined as $|t_{PLH} – t_{PHL}|$ of each channel of the same device.

5.7 Typical Characteristics

at T_A = 25°C (unless otherwise noted)

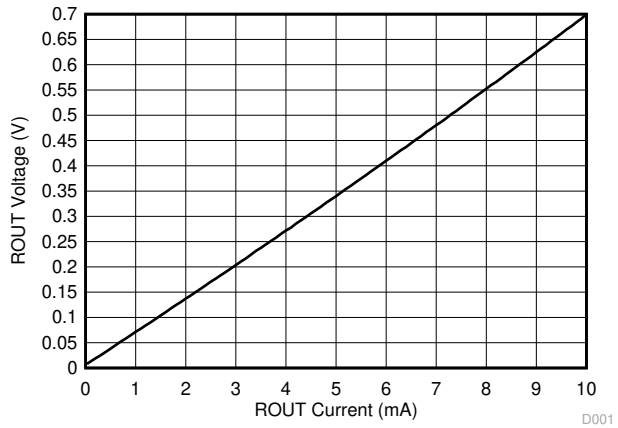


Figure 5-1. Receiver VOL vs Output Current

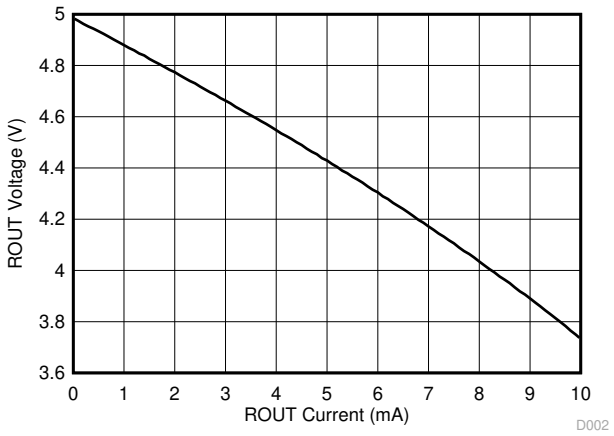


Figure 5-2. Receiver VOH vs Output Current

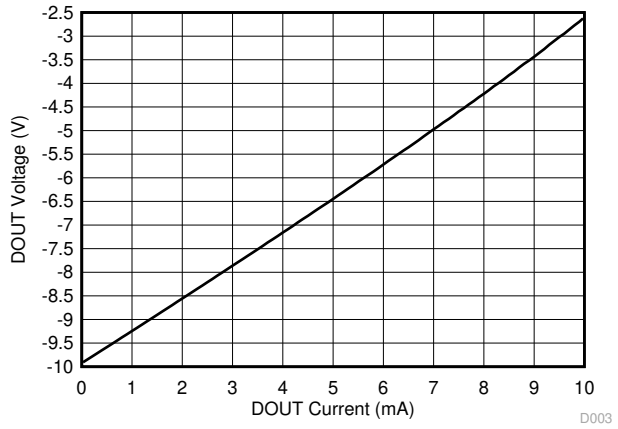


Figure 5-3. Driver VOL vs Output Current

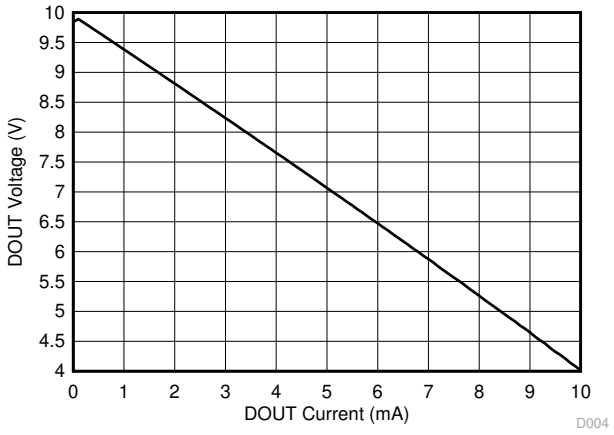


Figure 5-4. Driver VOH vs Output Current

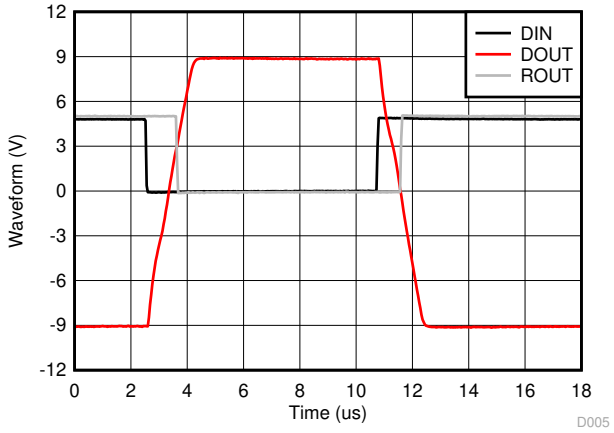
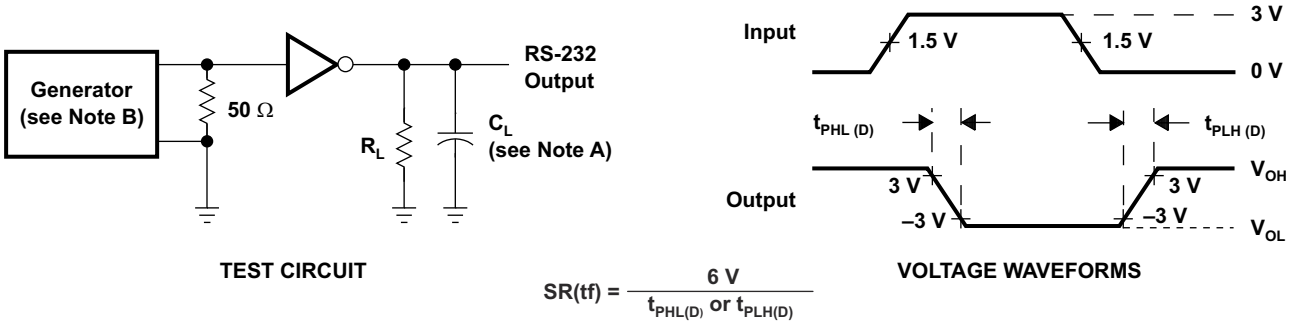


Figure 5-5. Driver and Receiver Loopback Waveforms

Parameter Measurement Information



TEST CIRCUIT

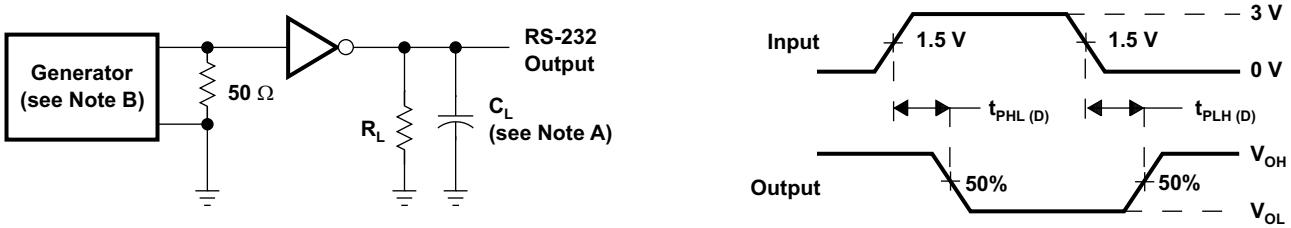
$$SR(tf) = \frac{6\ V}{t_{PHL(D)} \text{ or } t_{PLH(D)}}$$

VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 120kbit/s, Z_O = 50Ω, 50% duty cycle, t_r ≤ 10ns, t_f ≤ 10ns.

Figure 6-1. Driver Slew Rate



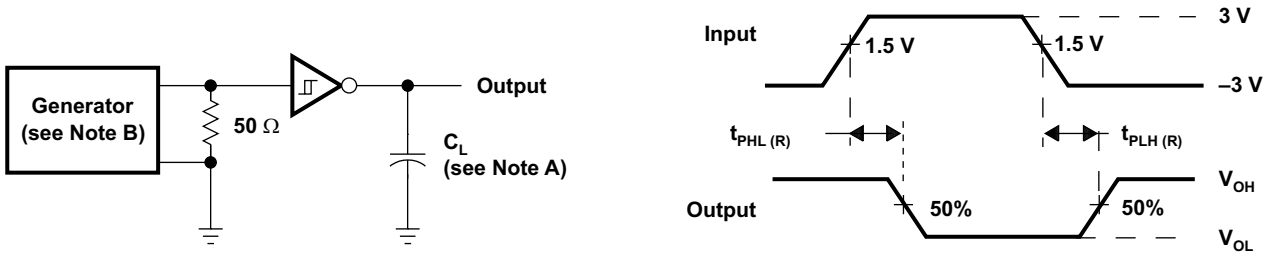
TEST CIRCUIT

VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR = 120kbit/s, Z_O = 50Ω, 50% duty cycle, t_r ≤ 10ns, t_f ≤ 10ns.

Figure 6-2. Driver Pulse Skew



TEST CIRCUIT

VOLTAGE WAVEFORMS

A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: Z_O = 50Ω, 50% duty cycle, t_r ≤ 10ns, t_f ≤ 10ns.

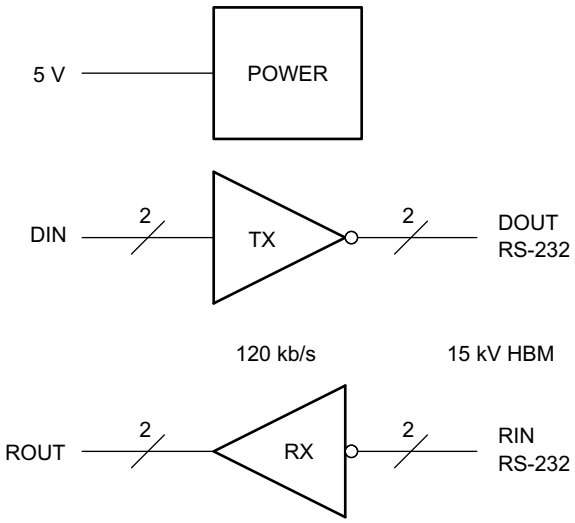
Figure 6-3. Receiver Propagation Delay Times

6 Detailed Description

6.1 Overview

The MAX202 is a dual driver and receiver that includes a capacitive voltage generator using four capacitors to supply TIA/EIA-232-F voltage levels from a single 5V supply. Each receiver converts TIA/EIA-232-F inputs to 5V TTL/CMOS levels. These receivers have shorted and open fail safe. The receiver can accept up to ±30V inputs and decode inputs as low as ±3V. Each driver converts TTL/CMOS input levels into TIA/EIA-232-F levels. Outputs are protected against shorts to ground.

6.2 Functional Block Diagram



6.3 Feature Description

6.3.1 Power

The power block increases and inverts the 5V supply for the RS-232 driver using a charge pump that requires four 0.1µF external capacitors.

6.3.2 RS-232 Driver

Two drivers interface standard logic levels to RS-232 levels. The driver inputs do not have internal pullup resistors. Do not float the driver inputs.

6.3.3 RS-232 Receiver

Two Schmitt trigger receivers interface RS-232 levels to standard logic levels. Each receiver has an internal 5-kΩ load to ground. An open input results in a high output on ROUT.

6.4 Device Functional Modes

6.4.1 V_{CC} Powered by 5V

The device is in normal operation when powered by 5V.

6.4.2 V_{CC} Unpowered

When MAX202 is unpowered, it can be safely connected to an active remote RS-232 device.

6.4.3 Truth Tables

Table 6-1 and Table 6-2 list the function for each driver and receiver (respectively).

Table 6-1. Function Table for Each Driver

INPUT DIN(1)	OUTPUT DOUT
L	H
H	L

(1) H = high level, L = low level

Table 6-2. Function Table for Each Receiver

INPUT RIN(1)	OUTPUT ROUT
L	H
H	L
Open	H

(1) H = high level, L = low level,
Open = input disconnected or connected driver off

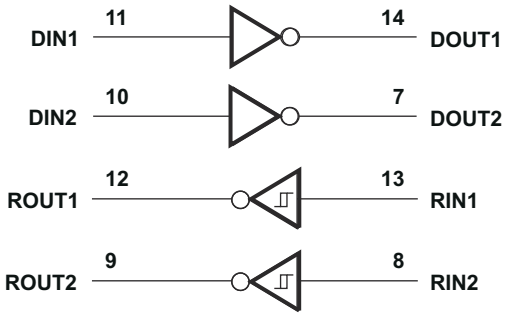


Figure 6-1. Logic Diagram (Positive Logic)

7 Application and Implementation

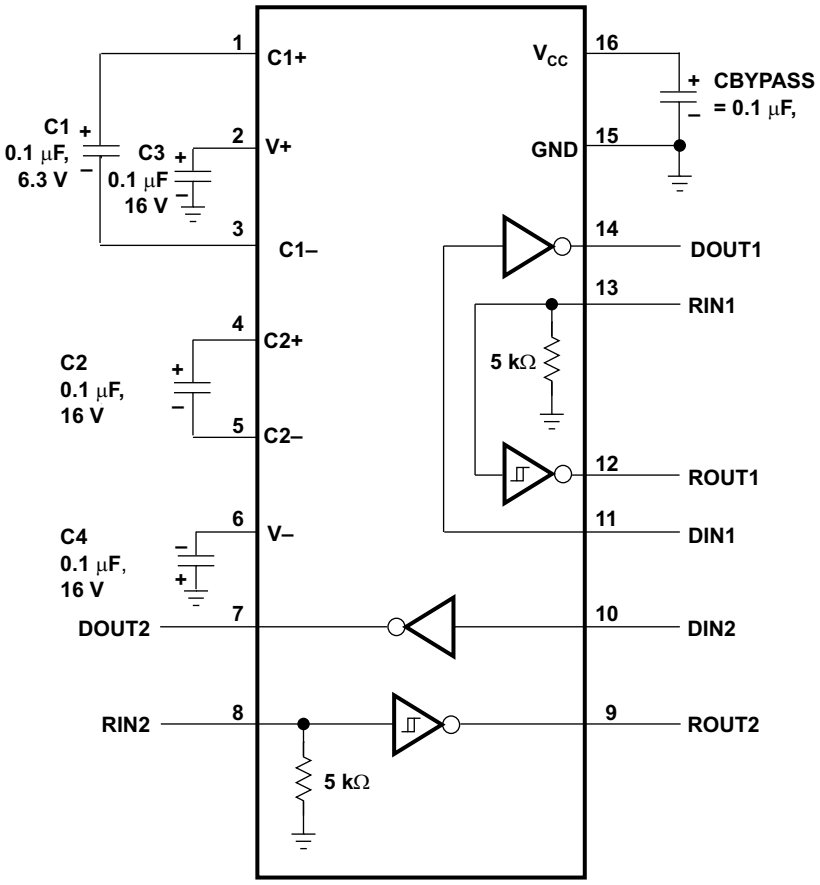
Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Application Information

For proper operation, add capacitors as shown in Figure 7-1. Pins 9 through 12 connect to UART or general purpose logic lines. RS-232 lines on pins 7, 8, 13, and 14 connect to a connector or cable.

7.2 Typical Application



A. C3 can be connected to V_{CC} or GND.
B. Resistor values shown are nominal.
C. Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they must be connected as shown.

Figure 7-1. Typical Operating Circuit and Capacitor Values

7.2.1 Design Requirements

- V_{CC} minimum is 4.5V and maximum is 5.5V.
- Maximum recommended bit rate is 120kbps.

7.2.2 Detailed Design Procedure

7.2.2.1 Capacitor Selection

The capacitor type used for C1 through C4 is not critical for proper operation. The MAX202 requires 0.1µF capacitors. Capacitors up to 10µF can be used without harm. Ceramic dielectrics are suggested for the 0.1µF capacitors. When using the minimum recommended capacitor values, make sure the capacitance value does not degrade excessively as the operating temperature varies. If in doubt, use capacitors with a larger (for example, 2×) nominal value. The capacitors' effective series resistance (ESR), which usually rises at low temperatures, influences the amount of ripple on V+ and V–.

Use larger capacitors (up to 10µF) to reduce the output impedance at V+ and V–.

Bypass V_{CC} to ground with at least 0.1µF. In applications sensitive to power-supply noise generated by the charge pumps, decouple V_{CC} to ground with a capacitor the same size as (or larger than) the charge-pump capacitors (C1 to C4).

7.2.2.2 ESD Protection

MAX202 devices have standard ESD protection structures incorporated on all pins to protect against electrostatic discharges encountered during assembly and handling. In addition, the RS-232 bus pins (driver outputs and receiver inputs) of these devices have an extra level of ESD protection. Advanced ESD structures were designed to successfully protect these bus pins against ESD discharge of ±15kV when powered down.

7.2.2.3 ESD Test Conditions

Stringent ESD testing is performed by TI based on various conditions and procedures. Please contact TI for a reliability report that documents test setup, methodology, and results.

7.2.2.4 Human-Body Model (HBM)

The HBM of ESD testing is shown in Figure 7-2. Figure 7-3 shows the current waveform that is generated during a discharge into a low impedance. The model consists of a 100-pF capacitor, charged to the ESD voltage of concern, and subsequently discharged into the device under test (DUT) through a 1.5-kΩ resistor.

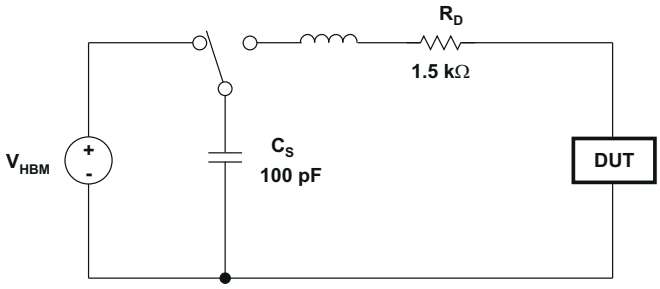


Figure 7-2. HBM ESD Test Circuit

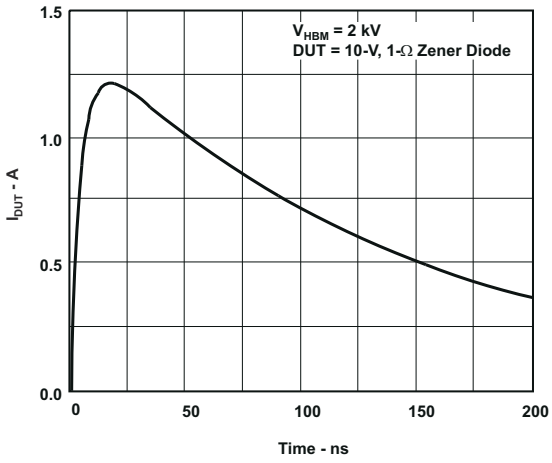
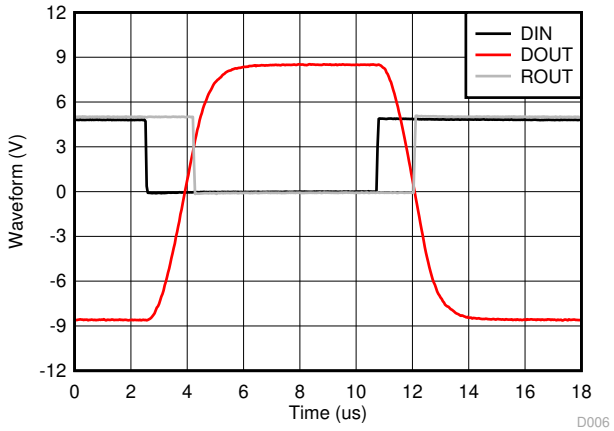


Figure 7-3. Typical HBM Current Waveform

7.2.3 Application Curve



120 kbit/s, 1-nF load

Figure 7-4. Driver and Receiver Loopback Signal

7.3 Power Supply Recommendations

The V_{CC} voltage must be connected to the same power source used for logic device connected to DIN and ROUT pins. V_{CC} must be between 4.5 V and 5.5 V.

7.4 Layout

7.4.1 Layout Guidelines

Keep the external capacitor traces short. This is more important on C1 and C2 nodes that have the fastest rise and fall times. For best ESD performance, make the impedance from MAX202 ground pin to the ground plane of the circuit board as low as possible. Use wide metal and multiple vias on both sides of ground pin.

7.4.2 Layout Example

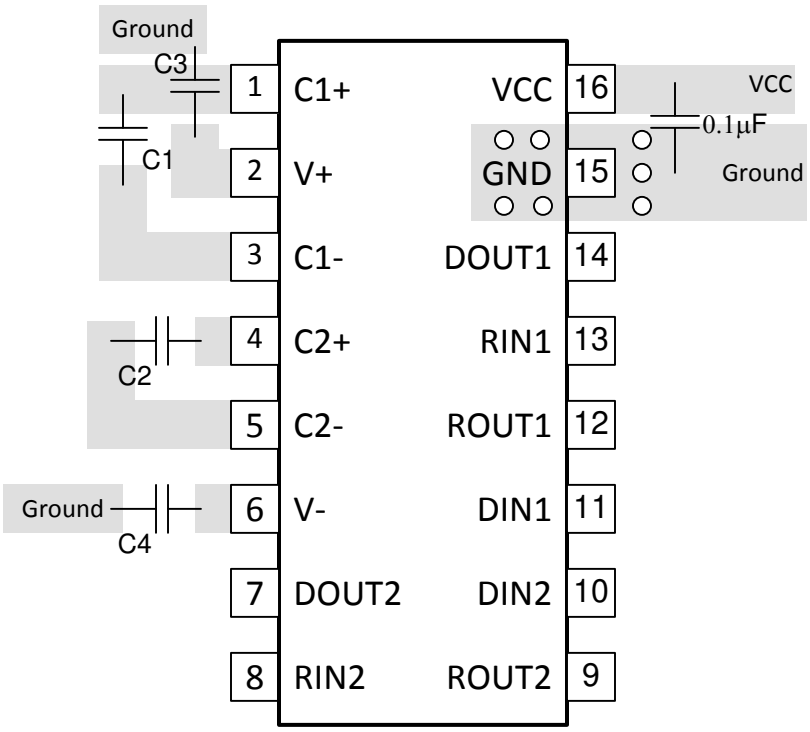


Figure 7-5. MAX202 Circuit Board Layout

8 Device and Documentation Support

8.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.2 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

8.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

8.4 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.5 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision F (September 2016) to Revision G (February 2024)	Page
• Changed the *Package Information* table	1
• Changed values in the *Thermal Information* table	4

Changes from Revision E (April 2007) to Revision F (September 2016)	Page
• Added *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section	1
• Removed the *Ordering Information* table; see POA at the end of the data sheet	1
• Changed values in the *Thermal Information* table to align with JEDEC standards	4

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
MAX202CD	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	0 to 70	MAX202C
MAX202CDR	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	0 to 70	MAX202C
MAX202CDW	Obsolete	Production	SOIC (DW) | 16	-	-	Call TI	Call TI	0 to 70	MAX202C
MAX202CPW	Obsolete	Production	TSSOP (PW) | 16	-	-	Call TI	Call TI	0 to 70	MA202C
MAX202CPWR	Obsolete	Production	TSSOP (PW) | 16	-	-	Call TI	Call TI	0 to 70	MA202C
MAX202ID	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-40 to 85	MAX202I
MAX202IDR	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX202I
MAX202IDR.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX202I
MAX202IDRE4	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX202I
MAX202IDW	Obsolete	Production	SOIC (DW) | 16	-	-	Call TI	Call TI	-40 to 85	MAX202I
MAX202IDWR	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX202I
MAX202IDWR.A	Active	Production	SOIC (DW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MAX202I
MAX202IPW	Obsolete	Production	TSSOP (PW) | 16	-	-	Call TI	Call TI	-40 to 85	MB202I
MAX202IPWR	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 85	MB202I
MAX202IPWR.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	MB202I

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

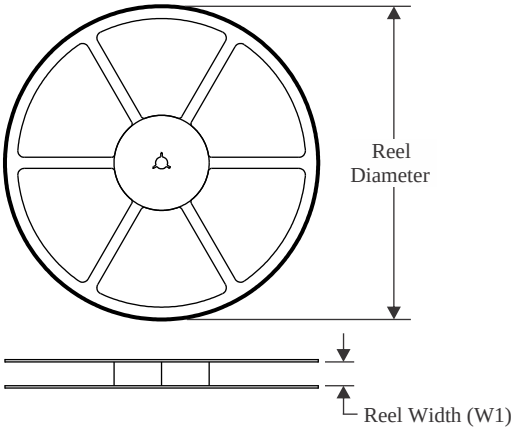
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

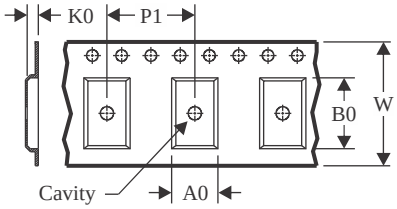
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

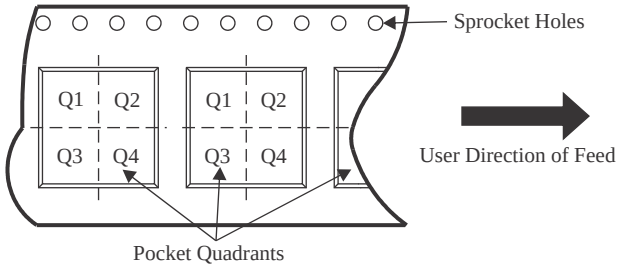


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

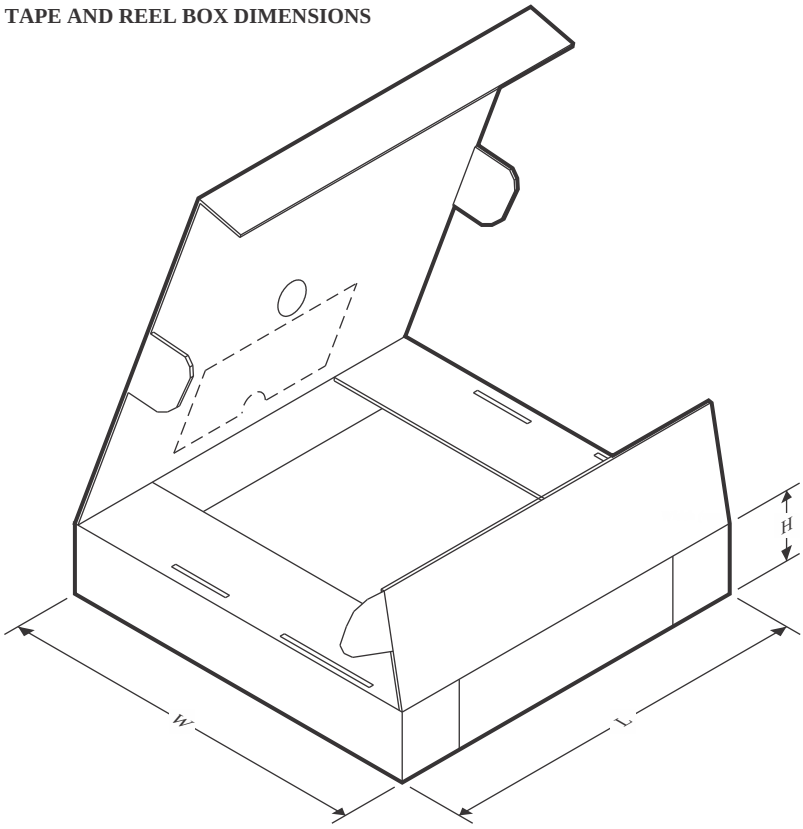
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MAX202IDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
MAX202IDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
MAX202IDWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
MAX202IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

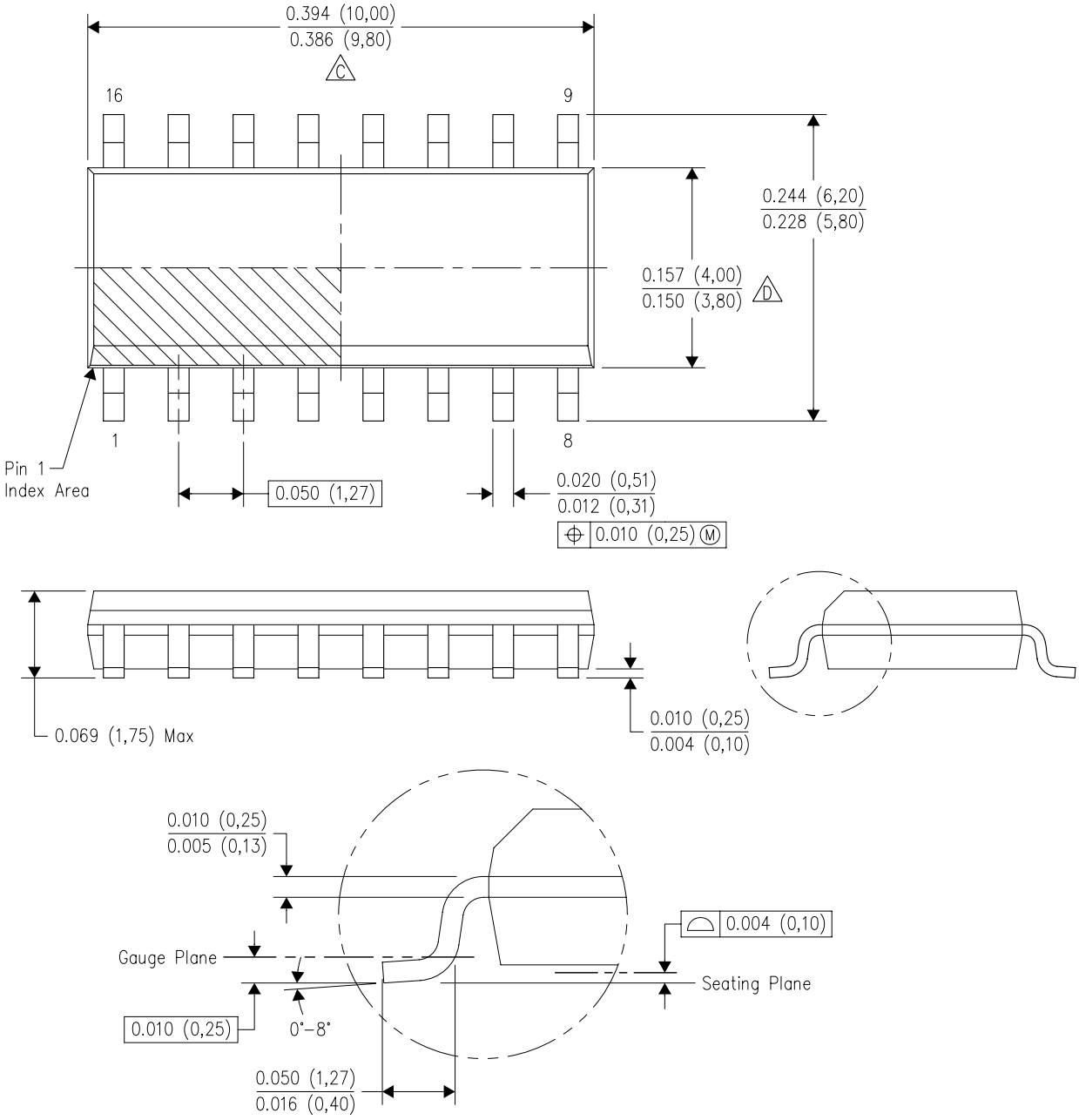
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MAX202IDR	SOIC	D	16	2500	353.0	353.0	32.0
MAX202IDR	SOIC	D	16	2500	340.5	336.1	32.0
MAX202IDWR	SOIC	DW	16	2000	350.0	350.0	43.0
MAX202IPWR	TSSOP	PW	16	2000	356.0	356.0	35.0

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

GENERIC PACKAGE VIEW

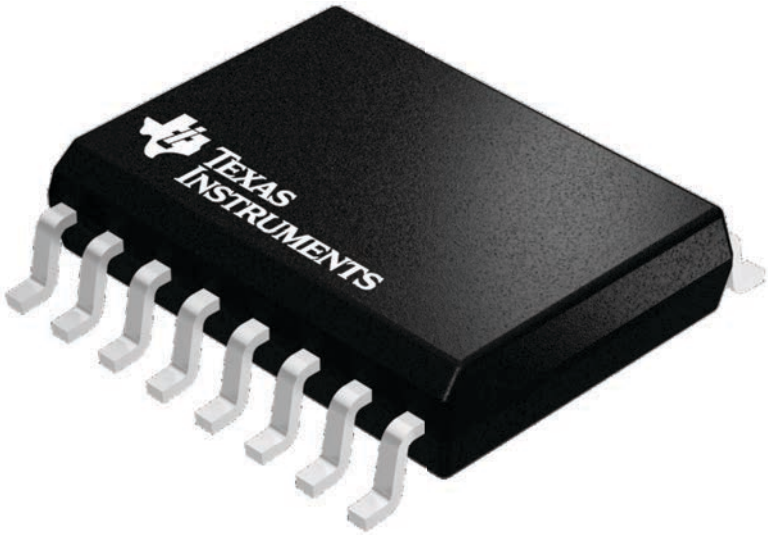
DW 16

SOIC - 2.65 mm max height

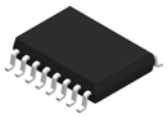
7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224780/A

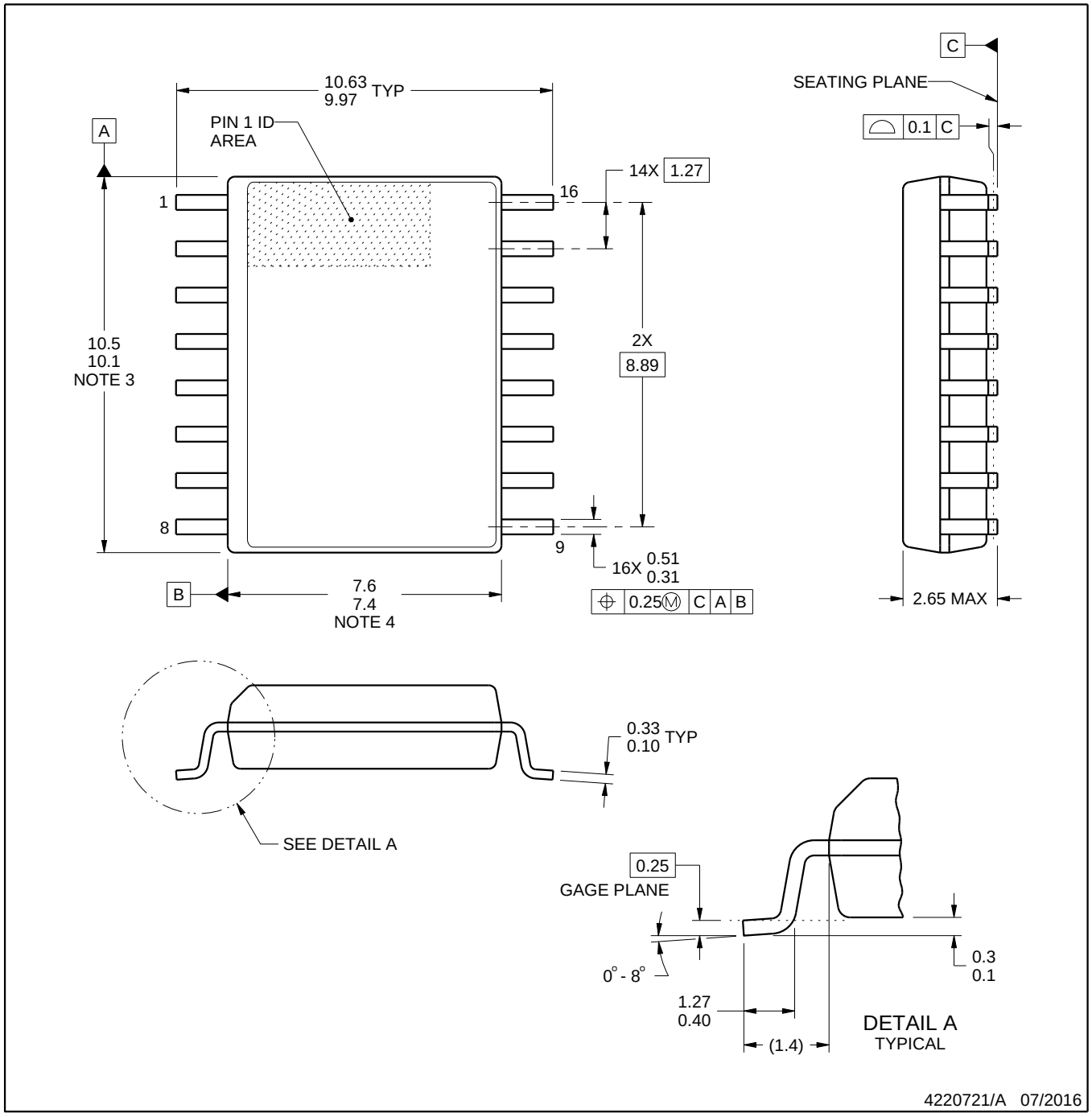


PACKAGE OUTLINE

DW0016A

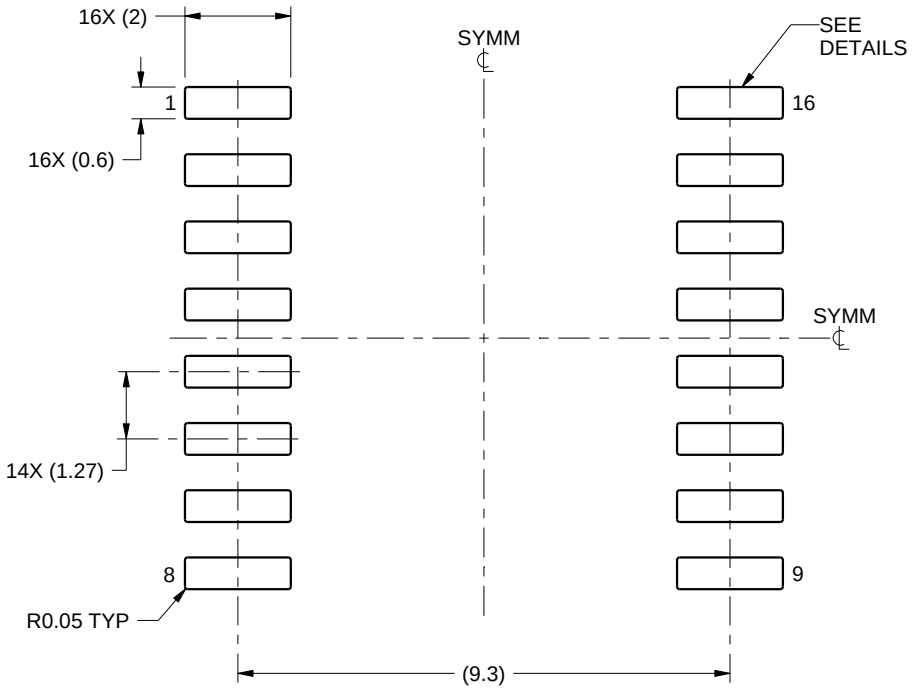
SOIC - 2.65 mm max height

SOIC

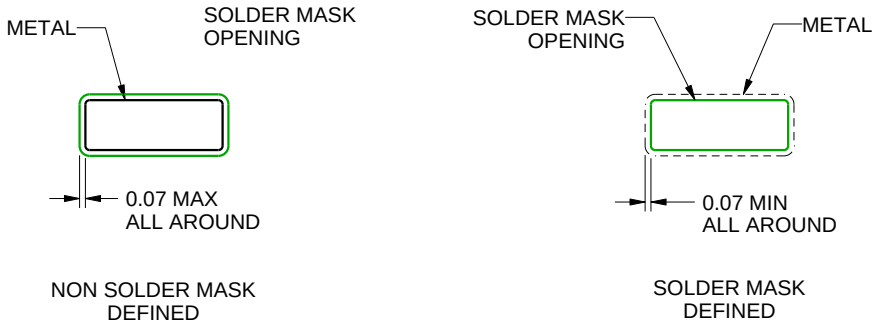


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:7X

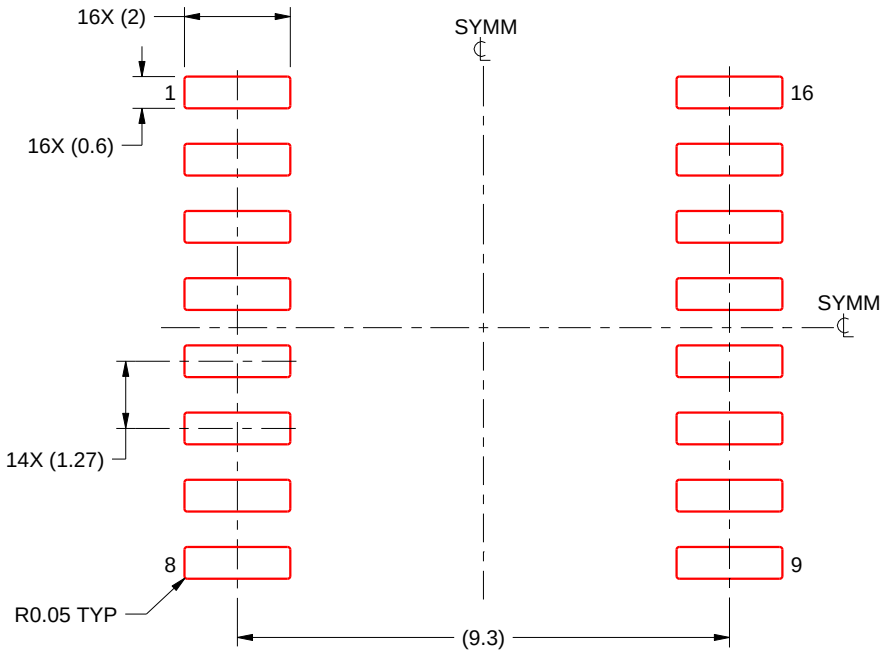


SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220721/A 07/2016

NOTES: (continued)

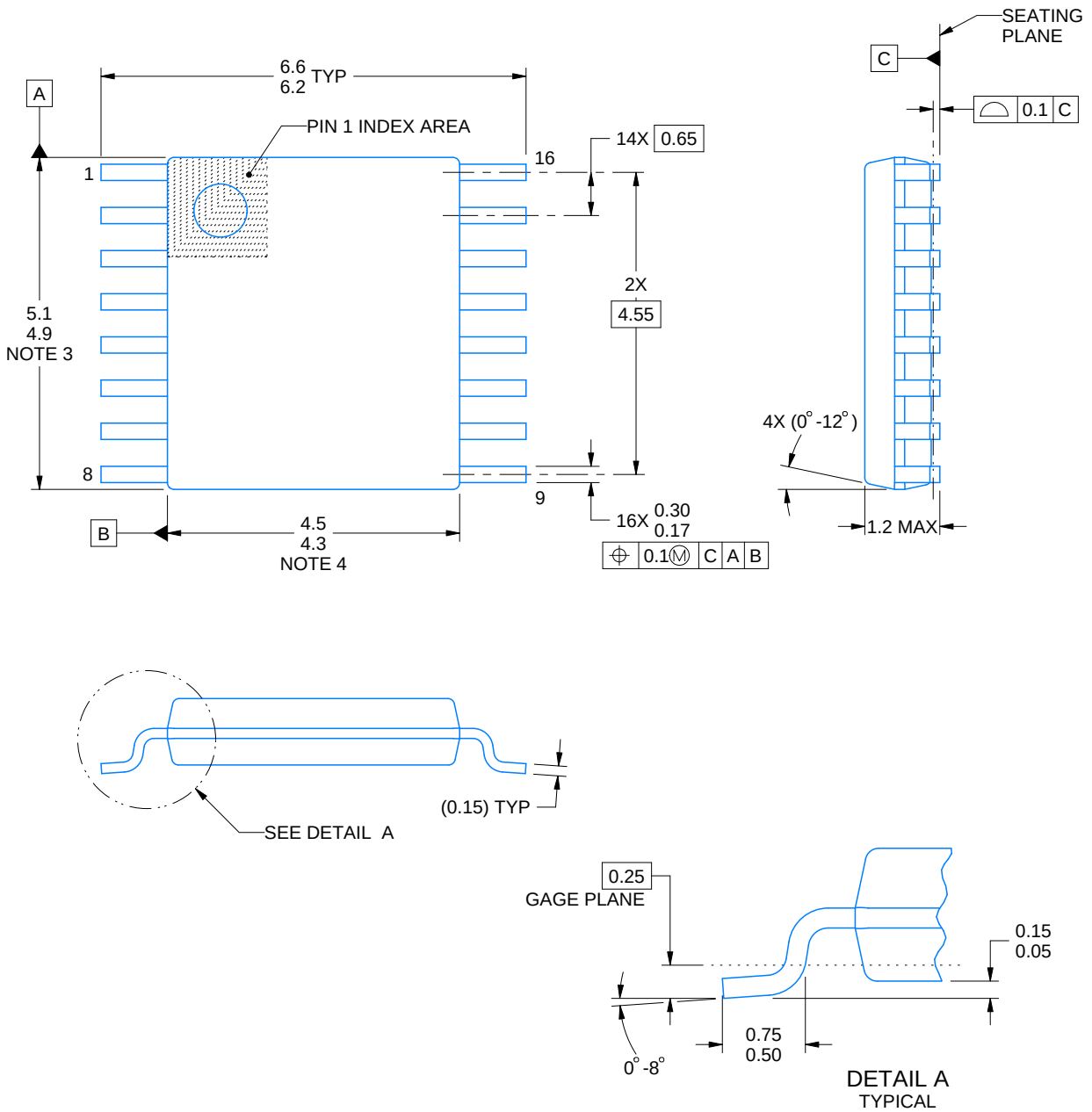
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

PW0016A

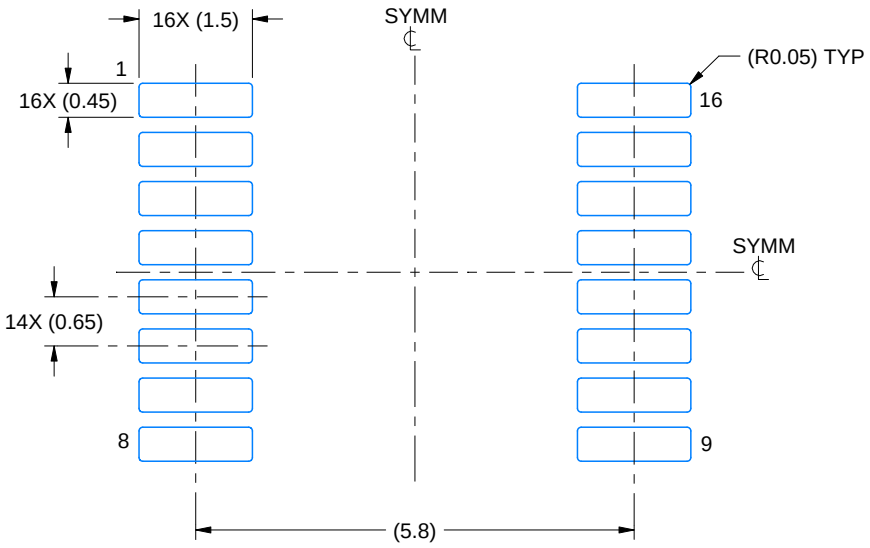
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



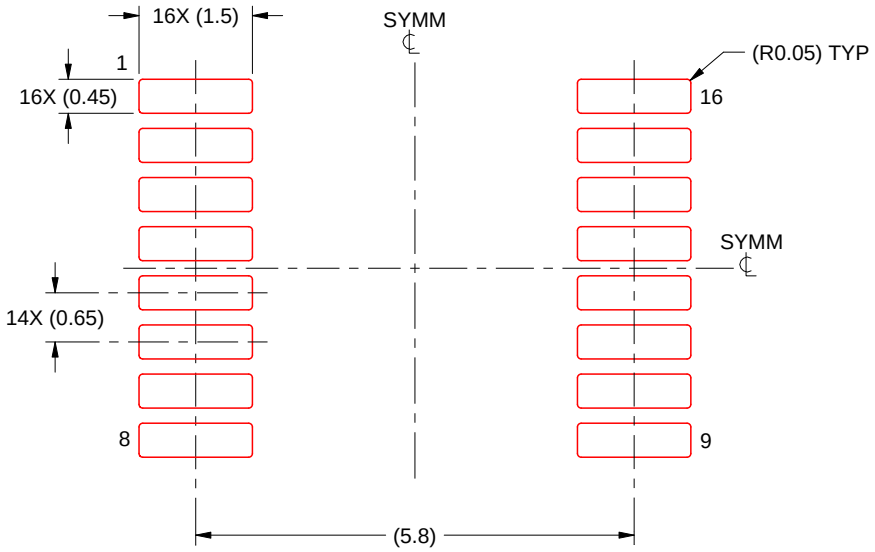
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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Last updated 10/2025